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SEMICONDUCTOR

# 2N5952

# **N-Channel RF Ampifier**

- This device is designed primarily for electronic switching applications such as low on resistance analog switching.
- Sourced from process 50.



1. Gate 2. Source 3. Drain

# Absolute Maximum Ratings \* T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>DG</sub>	Drain-Gate Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	-30	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### NOTES:

These ratings are based on a maximum junction temperature of 150 degrees C.
These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

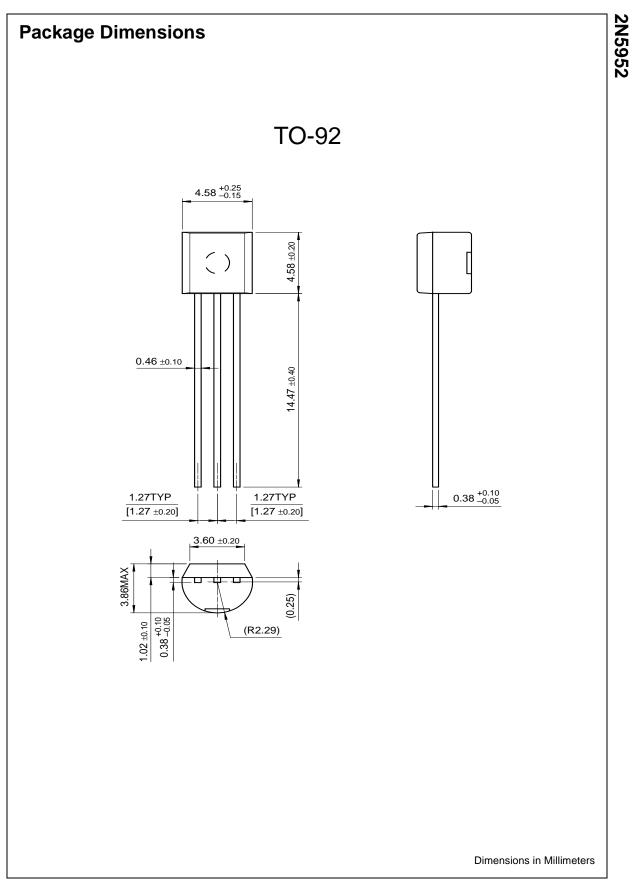
## Electrical Characteristics T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Chara	cteristics					
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$V_{DS} = 0, I_G = -1.0 \mu A$	-30			V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$			-1.0	nA
V <sub>GS(off)</sub>	Gate-Source Cutoff Voltage	V <sub>DS</sub> = 15V, I <sub>D</sub> = 100nA	-1.3		-3.5	V
On Chara	cteristics					
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0	4.0		8.0	mA
Small Sig	nal Characteristics					
9 <sub>fs</sub>	Forward Transfer Conductance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0, f = 1.0kHz	2000		6500	μmhos
9 <sub>os</sub>	Output Conductance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0, f = 100MHz			75	μmhos
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0, f = 1.0MHz			6.0	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0, f = 1.0MHz			2.0	pF
NF	Noise Figure	$V_{DS} = 15V, R_G = 1.0k\Omega,$ f = 1.0kHz			2.0	dB

\* Pulse Test: Pulse Width ≤ 300ms, Duty Cycle ≤ 1.0%

## Thermal Characteristics TA=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
PD	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W



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